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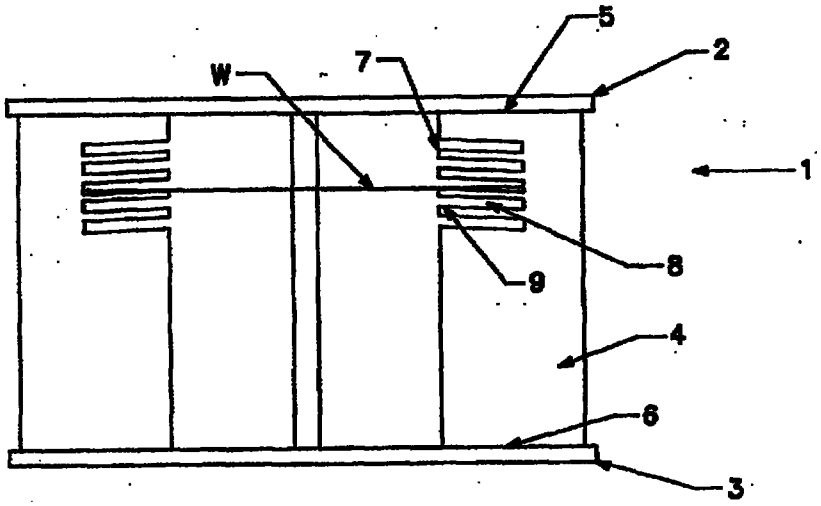
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(54) Title: SLIP FREE VERTICAL RACK DESIGN



(57) Abstract

The present invention relates to a vertical rack for supporting a plurality of semiconductor wafers in a spaced, substantially horizontal, parallel relation, the vertical rack comprising: a) a vertical support means, and b) a plurality of vertically spaced, horizontal support means extending substantially horizontally from the vertical support means to define a plurality of support levels for supporting the wafers, wherein the horizontal support means are projections, each projection comprising an arm terminating in a wafer platform such that the innermost contact between at least one wafer platform of each support level and its supported wafer is in the region of between 20 % and 80 % of the wafer radius, measured from the edge of the wafer, and wherein the arm projects at a continuous upward incline and terminates in the wafer platform.